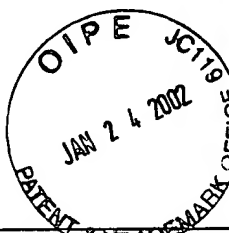


SUPPLEMENTAL INFORMATION DISCLOSURE CITATION PTO-1449			Atty Docket 42496/0269250		Serial No. 09/941,360	
Date Mailed: August 28, 2001						
			Applicant: Talieh, et al.		Filing Date August 28, 2001	
US PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
DN	3959089	05/25/76	Watts			
DN	4610772	09/09/86	Palnik			
DN	5024735	06/18/91	Kadija			
DN	6004880	12/21/99	Liu et al			
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DN	5833820	11/10/98	Dubin			
DN	4,919,769	4/1990	Lin	205	206	
EXAMINER <i>Donald R. Valentini</i>			DATE CONSIDERED <i>6-03</i>			

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

SUPPLEMENTAL INFORMATION DISCLOSURE CITATION			Atty Docket 42496/0269250		Serial No. 09/941,360		
PTO-1449			Applicant: Talieh, et al.				
Date Mailed: August 28, 2001							
			Filing Date August 28, 2001		Group Art Unit: 1741		
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
<i>DN</i>	DE 2008664	09/09/71	Germany				
<i>DN</i>	DE 4324330	03/02/94	Germany				
<i>DN</i>	EP 0903774 A2	03/24/99	EP				
<i>DN</i>	EP 0960693 A2	12/01/99	EP				
<i>DN</i>	WO 95/00295	01/05/95	PCT				
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
<i>DN</i>	M. Rubinstein, "Tampongalvanisieren in de Praxis, Teil 2." GALVANOTECHNIK, Vol. 79, No. 10, 1988, pp. 3263-3270 <i>No work</i>						
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<i>DN</i>	Alan C. West, Chin-Chang Cheng and Brett C. Baker, "Pulse Reverse Copper Electrodeposition in High Aspect Ratio Trenches and Vias", September 1998, pp. .070-3073						
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